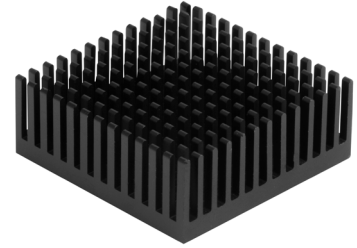




**MODEL:** HSB27-434316 | **DESCRIPTION:** HEAT SINK

**FEATURES**

- BGA design
- top mount
- aluminum alloy



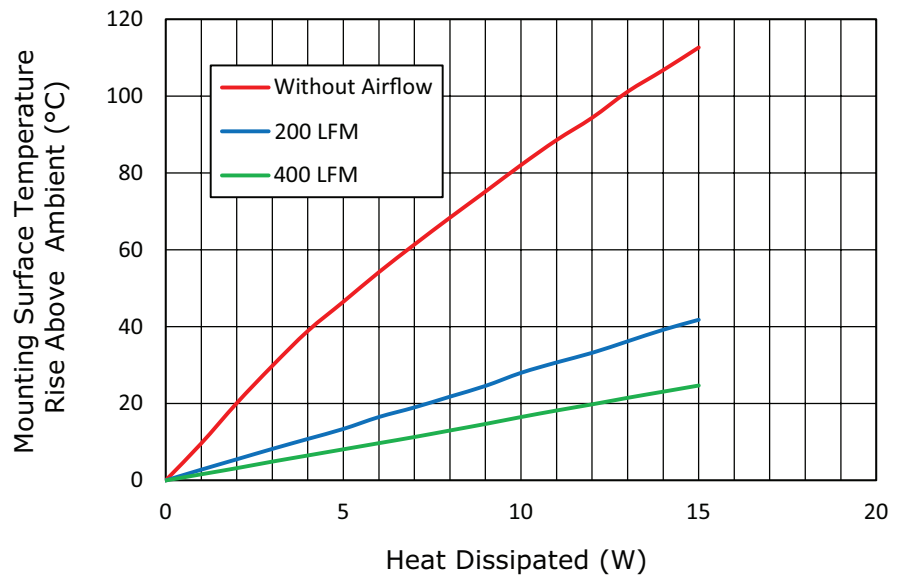
**MODEL**

HSB27-434316	thermal resistance <sup>1</sup>				power dissipation <sup>1</sup>
	@ 75°C ΔT, nat conv [°C/W]	@ 1 W, nat conv [°C/W]	@ 1 W, 200 LFM [°C/W]	@ 1 W, 400 LFM [°C/W]	@ 75°C ΔT, nat conv [W]
	8.35	9.6	2.8	1.6	8.98

Note: 1. See performance curves for full thermal resistance details.

**PERFORMANCE CURVES**

Power [W]	Heatsink Temperature Rise Above Ambient (ΔT = T <sub>hs</sub> - T <sub>a</sub> ) [°C]		
	Natural Conv.	200 LFM	400 LFM
0	0	0	0
1	9.6	2.8	1.6
2	20.1	5.5	3.2
3	29.8	8.2	4.9
4	38.9	10.8	6.5
5	46.5	13.4	8.1
6	54.2	16.5	9.7
7	61.4	19.0	11.3
8	68.4	21.8	13.0
9	75.2	24.6	14.7
10	82.1	28.0	16.5
11	88.6	30.7	18.2
12	94.4	33.2	19.8
13	101.2	36.2	21.5
14	106.8	39.2	23.1
15	112.7	41.8	24.7



T<sub>hs</sub>: "hot spot" temperature measured on the heatsink  
 T<sub>a</sub>: ambient temperature

## MECHANICAL DRAWING

units: mm  
tolerance:  $\pm 0.5$  mm

MATERIAL	AL 6063-T5
FINISH	black anodized
WEIGHT	35.6 g

